## BEST AVAILABLE COPY

## In The Claims

Please amend Claim 1 and add new Claim 17 as follows:

1. (Currently amended) An etching agent for <a href="etching">etching</a> copper <a href="mailto:in an etching">in an etching</a> <a href="mailto:process">process</a> comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of <a href="mailto:about-10.01%">about-10.01%</a> to about 23.31% by weight of the etching agent, <a href="mailto:said-etching-agent-etching-the-copper-at-an-approximately-uniform-rate-throughout-the-etching-process">etching-process</a>.



2. (Original) An etching agent for copper according to Claim 1, wherein said aqueous solution contains acetic acid.

Claims 3-16 (Cancelled)

17. (New) An etching agent according to claim 1, wherein said etching agent is capable of selectively etching the copper.